



Substrate Integrated Waveguide (SIW) and Its Applications II

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Message from the Guest Editor

Dear Colleagues,

During the last decade, substrate integrated waveguide (SIW) technology has been largely implemented for the construction of numerous microwave devices and circuits based on innovative solutions or re-proposing, by following a quasi-planar approach, well-known functionalities of classical waveguide-based components/systems. The possibility of fabricating shielded structures by employing planar geometries has provided an amazing way to fabricate innovative resonators exhibiting very high quality factors suitable for filter and oscillator applications, efficient radiating structures. Multi-layered printed circuit board (PCB) or low-temperature co-fired ceramic (LTCC) technologies and the SIW approach allow a high feasibility, planar integration and packaging degree to be reached. As a consequence, the possibility of fabricating complex structures at low cost fulfils the increasing demand of highly sophisticated antennas for satellite communication, 5G and new generation wireless systems, terahertz systems, biomedicine, and a number of other applications.

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